

# PATENT ASSIGNMENT

Electronic Version v1.1

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Manolito Fabres Galera	09/03/2008
Leocadio Morona Alabin	09/03/2008
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Fairchild Semiconductor Corporation
<b>Street Address:</b>	82 Running Hill Rd.
<b>City:</b>	South Portland
<b>State/Country:</b>	MAINE
<b>Postal Code:</b>	04106
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12199065
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(801)321-4893
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<b>ATTORNEY DOCKET NUMBER:</b>	11948.63
<b>NAME OF SUBMITTER:</b>	Kenneth E. Horton
<b>Total Attachments: 2</b> source=Assignment_63#page1.tif source=Assignment_63#page2.tif	

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**PATENT**  
**REEL: 024046 FRAME: 0023**

### ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, the person(s) named below (referred to as "INVENTOR" whether singular or plural) has sold, assigned, and transferred and does hereby sell, assign, and transfer to Fairchild Semiconductor Corporation, having a place of business at 82 Running Hill Rd. MS 35-4E, South Portland, ME. 04106 ("ASSIGNEE"), for itself and its successors, transferees, and assignees, the following:

1. The entire worldwide right, title, and interest in all inventions and improvements ("SUBJECT MATTER") that are disclosed in the application for United States Letters Patent entitled: Micro-Layered Lead Frame Semiconductor Packages

("APPLICATION"), which:

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is to be filed herewith (attorney docket no. 11948.63)

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was filed on August 27, 2008 now bearing U.S. Serial No.: 12/199,065;

And

2. The entire worldwide right, title, and interest in and to:  
(a) the APPLICATION, including any right of priority; (b) any divisional, continuation, substitute, renewal, reissue, and other related applications which have been or may be filed in the United States or elsewhere in the world; and (c) any patents which may be granted on the applications set forth in (a) and (b) above.

INVENTOR agrees that ASSIGNEE may apply for and receive patents for SUBJECT MATTER in ASSIGNEE's own name.

INVENTOR agrees to do the following, when requested, and without further consideration, in order to carry out the intent of this Assignment: (1) execute all oaths, assignments, powers of attorney, applications, and other papers necessary or desirable to fully secure to ASSIGNEE the rights, titles and interests herein conveyed; (2) communicate to ASSIGNEE all known facts relating to the SUBJECT MATTER; and (3) generally do all lawful acts that ASSIGNEE shall consider desirable for securing, maintaining, and enforcing worldwide patent protection relating to the SUBJECT MATTER and for vesting in ASSIGNEE the rights, titles, and interests herein conveyed. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE hereunder.


INVENTOR represents that INVENTOR has the right, title, and interests to convey as set forth herein, and covenants with ASSIGNEE that the INVENTOR has made or will make hereafter no assignment, grant, mortgage, license, or other agreement affecting the rights, titles, and interests herein conveyed.

INVENTOR:

  
Manglito Fabres Galera

Date 03 SEP 2008

INVENTOR:

  
Leocadio Morona Alabin

Date 03 SEP 2008